



Advance Product Change Notification

201704020A

Issue Date: 01-May-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Change Category

☐ Wafer Fab Process

☐ Wafer Fab Materials

☒ Wafer Fab Location

☐ Assembly Process

☐ Assembly Materials

☐ Assembly Location

☐ Product Marking

☐ Mechanical Specification

☐ Packing/Shipping/Labeling

☐ Test Location

☐ Test Process

☐ Test Equipment

☐ Design

☐ Errata

☐ Electrical spec./Test coverage

**PRE ALERT: GRADE 1
MC9S12G64/48 AND
MC9S12G32/16 FAB EXPANSION
(NXP-ATMC TO TSMC3)**

Details of this Planned Change

To meet the increasing demand for the Grade 1 MC9S12G64/48 and MC9S12G32/16, NXP is announcing the introduction of Taiwan Semiconductor Manufacturing Company Fab 3 (TSMC3), Hsinchu, Taiwan as a dual source wafer manufacturing location for this family. TSMC3 will be qualified with Copper wirebond material. Expected qualification of TSMC3 is July 2017. An update to this notification with qualification results will be issued at that time.

Supplemental information on Prototype Part numbers for sample orders, Key Dates for the Expansion, and the part number Nomenclature Decoder are attached.

Why do we Plan this Change

The Fab manufacturing site capacity expansion to TSMC3 will improve NXP's ability to meet increasing customer demand and still maintain supply from the original Fab (ATMC).

Identification of Affected Products

Top side marking

The last 4 digits of the Mask ID marking will change from N75C to N55V for MC9S12G64/48 and N48A to N57V for MC9S12G32/16.

The Part Number Maskset Identifier Digit will be set to J instead of F.

Product Availability

Sample Information

Samples are available from

Samples are available from 17-June-2017, please refer to attachment for detail sample part number.

Date above reflects Qual Intent samples.

Production

Planned first shipment 17-Oct-2017

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Fab Expansion. No Depletion of Inventory required.

Timing and Logistics

The Self Qualification Report will be ready on 17-Jul-2017.

The Final PCN is planned to be issued on: 17-Jul-2017.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 31-May-2017.

The SQR will be ready on 17-Jul-2017. The Final PCN is planned to be issued on 17-Jul-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Numbers

S9S12G48F0CLF

S9S12G48F1CLC

S9S12G48F0CLF

S9S12G48F1CLC